TEXAS INSTRUMENTS

TPL0401A-10-Q1
TPL0401B-10-Q1

JAJSCP7 – NOVEMBER 2016

TPL0401x-10-Q1 128タップ・シングル・チャネル・デジタル・ポテンショメータ、I²Cインターフェイス付き

1 特長

- シングル・チャネル、128ポジションの分解能
- エンド・ツー・エンド抵抗値10kΩのオプション
- 低温度ドリフト係数: 22ppm/℃
- I²Cシリアル・インターフェイス
- 2.7V～5.5Vの単電源で動作
- 抵抗誤差: ±20%
- AバージョンとBバージョンで異なるI²Cアドレス
- L端子を内部に備え、GNDに接続
- 動作温度範囲: -40℃～+125℃
- 業界標準のSC70パッケージで供給
- JESD 22に従ってESD性能をテスト済み
  - 人体モデルで2000V (A114-B、クラスII)

2 アプリケーション

- 機械式ポテンショメータの置換
- 可変電源
- 可変ゲイン・アンプとオフセット・トリミング
- 目標スレッショルドの高精度な較正
- センサのトリミングと較正

3 概要

TPL0401x-10-Q1デバイスは、128のワイパー位置を有するシングル・チャネル、リニア・テーパー・デジタル・ポテンショメータです。TPL0401x-10-Q1は、“L”端子が内部にありGNDに接続されています。ワイパーの位置は、I²Cインターフェイスを使用して調整できます。TPL0401x-10-Q1は、6ピンのSC70パッケージで供給され、仕様温度範囲は -40°C～+125°Cです。デバイスのエンド・ツー・エンド抵抗値は10kΩであり、2.7V～5.5Vの電源電圧範囲で動作できます。この種の製品は、低消費電力DDR3メモリ用基準電圧の調整に広く使用されています。

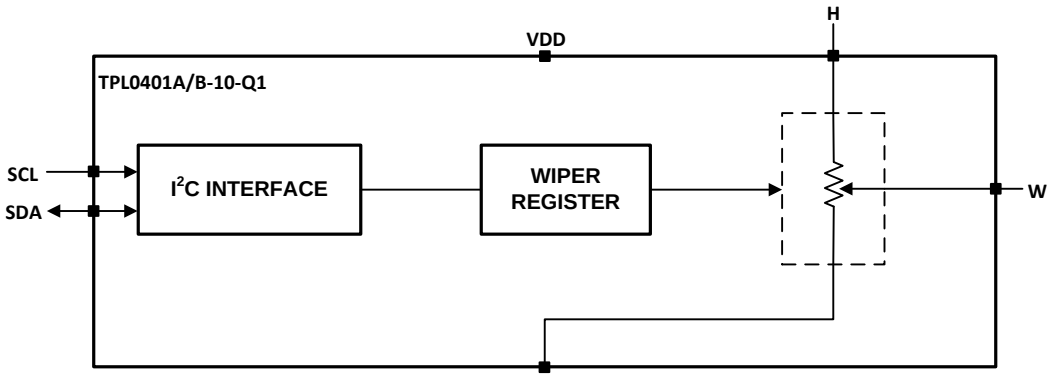
TPL0401x-10-Q1は、“L”端子が内部にありGNDに接続されています。

製品情報(1)

型番	パッケージ	本体サイズ(公称)
TPL0401A-10-Q1 TPL0401B-10-Q1	SC70 (6)	2.00mm×1.25mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。

概略回路図



目次

4 改訂履歴

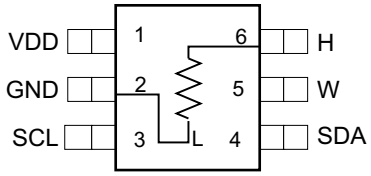
日付	改訂内容	注
2016年11月	*	初版

5 Device Comparison Table

PART NUMBER	END-TO-END RESISTANCE	I^2C ADDRESS
TPL0401A-10-Q1	10 kΩ	010 1110 (0×2E)
TPL0401B-10-Q1	10 kΩ	011 1110 (0×3E)

6 Pin Configuration and Functions

DCK Package
6-Pin SC70
Top View



Pin Functions

PIN		TYPE	DESCRIPTION
NO.	NAME		
1	VDD	Power	Positive supply voltage
2	GND	—	Ground
3	SCL	I	I^2C Clock
4	SDA	I/O	I^2C Data
5	W	I/O	Wiper terminal
6	H	I/O	High terminal
—	L	I/O	Low terminal (Internally connected to GND)

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

			MIN	MAX	UNIT
V_{DD}	Supply voltage	V_{DD} to GND	–0.3	7	V
I_H, I_L, I_W	Continuous current			±5	mA
V_I	Digital input pins (SDA, SCL)		–0.3	V_{DD} + 0.3	V
	Potentiometer pins (H, W)		–0.3	V_{DD} + 0.3	
$T_{J(MAX)}$	Maximum junction temperature			130	°C
T_{stg}	Storage temperature		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

7.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 (1)	±2500	V
		Charged-device model (CDM), per AEC Q100-011	±1000	

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{DD}	Supply voltage	2.7	5.5	V
V_W,V_H, SDA, SCL	Terminal voltage	0	V_{DD}	V
V_{IH}	Voltage input high (SCL, SDA)	0.7 × V_{DD}	V_{DD}	V
V_{IL}	Voltage input low (SCL, SDA)	0	0.3 × V_{DD}	V
I_W	Wiper current	–2	2	mA
T_A	Ambient operating temperature	–40	125	°C

7.4 Thermal Information

THERMAL METRIC (1)		TPL0401x-10-Q1 DCK (SC70) 6 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	234	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	110.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	79	°C/W
ψ_{JT}	Junction-to-top characterization parameter	7.2	°C/W
ψ_{JB}	Junction-to-board characterization parameter	77	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

7.5 Electrical Characteristics

Typical values are specified at 25°C and V_{DD} = 3.3 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
R_{TOTAL}	End-to-end resistance		8	10	12	kΩ
R_H	Terminal resistance			100	200	Ω
R_W	Wiper resistance			35	100	Ω

Electrical Characteristics (continued)

Typical values are specified at 25°C and V_{DD} = 3.3 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
C_H	Terminal capacitance			10		pF
C_W	Wiper capacitance			11		pF
TC_R	Resistance temperature coefficient			22		ppm/°C
$I_{DD(STBY)}$	V_{DD} standby current	–40°C to +105°C			0.5	µA
		–40°C to +125°C			1.5	
I_{IN-DIG}	Digital pins leakage current (SCL, SDA Inputs)		–2.5		2.5	µA
SERIAL INTERFACE SPECS (SDA, SCL)						
V_{IH}	Input high voltage		0.7 × V_{DD}		V_{DD}	V
V_{IL}	Input low voltage		0		0.3 × V_{DD}	V
V_{OL}	Output low voltage	SDA Pin, I_{OL} = 4 mA			0.4	V
C_{IN}	Pin capacitance	SCL, SDA Inputs		7		pF
VOLTAGE DIVIDER MODE (V_H = V_{DD}, V_W = Not Loaded)						
INL (1)(2)	Integral non-linearity		–0.5		0.5	LSB
DNL (3)(2)	Differential non-linearity		–0.25		0.25	LSB
ZS_{ERROR} (4)(5)	Zero-scale error		0	0.75	1.5	LSB
FS_{ERROR} (6)(5)	Full-scale error		–1.5	–0.75	0	LSB
T_{CV}	Ratiometric temperature coefficient	Wiper set at mid-scale		4		ppm/°C
BW	Bandwidth	Wiper set at mid-scale, C_{LOAD} = 10 pF		2862		kHz
T_{SW}	Wiper settling time	See Figure 10		0.152		µs
THD+N	Total harmonic distortion	V_H = 1 V_{RMS} at 1 kHz, measurement at W		0.03		%
RHEOSTAT MODE (V_H = V_{DD}, V_W = Not Loaded)						
RINL (7)(8)	Rheostat mode integral non-linearity		–1		1	LSB
RDNL (9)(8)	Rheostat mode differential non-linearity		0.5		0.5	LSB
R_{OFFSET} (10)(11)	Rheostat-mode zero-scale error		0	0.75	2	LSB

(1) INL = (($V_{MEAS[code\ x]}$ – $V_{MEAS[code\ 0]}$) / LSB) – [code x]
(2) LSB = ($V_{MEAS[code\ 127]}$ – $V_{MEAS[code\ 0]}$) / 127
(3) DNL = (($V_{MEAS[code\ x]}$ – $V_{MEAS[code\ x-1]}$) / LSB) – 1
(4) ZS_{ERROR} = $V_{MEAS[code\ 0]}$ / IDEAL_LSB
(5) IDEAL_LSB = V_H/ 128
(6) FS_{ERROR} = [($V_{MEAS[code\ 127]}$ – V_H) / IDEAL_LSB] + 1
(7) RINL = (($R_{MEAS[code\ x]}$ – $R_{MEAS[code\ 0]}$) / RLSB) – [code x]
(8) RLSB = ($R_{MEAS[code\ 127]}$ – $R_{MEAS[code\ 0]}$) / 127
(9) RDNL = (($R_{MEAS[code\ x]}$ – $R_{MEAS[code\ x–1]}$) / RLSB) – 1
(10) R_{OFFSET} = $R_{MEAS[code\ 0]}$ / IDEAL_RLSB
(11) IDEAL_RLSB = R_{TOT} / 128

7.6 Timing Requirements

		MIN	MAX	UNIT
STANDARD MODE				
f_{SCL}	I^2C Clock frequency	0	100	kHz
t_{SCH}	I^2C Clock high time	4		µs
t_{SCL}	I^2C Clock low time	4.7		µs
t_{sp}	I^2C Spike time	0	50	ns
t_{SDS}	I^2C Serial data setup time	250		ns

Timing Requirements (continued)

		MIN	MAX	UNIT
t_{SDH}	I^2C Serial data hold time	0		ns
t_{ICR}	I^2C Input rise time		1000	ns
t_{ICF}	I^2C Input fall time		300	ns
t_{OCF}	I^2C Output fall time, 10 pF to 400 pF bus		300	ns
t_{BUF}	I^2C Bus free time between stop and start	4.7		µs
t_{STS}	I^2C Start or repeater start condition setup time	4.7		µs
t_{STH}	I^2C Start or repeater start condition hold time	4		µs
t_{SPS}	I^2C Stop condition setup time	4		µs
$t_{VD(DATA)}$	Valid data time, SCL low to SDA output valid		1	µs
$t_{VD(ACK)}$	Valid data time of ACK condition, ACK signal from SCL low to SDA (out) low		1	µs
FAST MODE				
f_{SCL}	I^2C Clock frequency	0	400	kHz
t_{SCH}	I^2C Clock high time	0.6		µs
t_{SCL}	I^2C Clock low time	1.3		µs
t_{sp}	I^2C Spike time	0	50	ns
t_{SDS}	I^2C Serial data setup time	100		ns
t_{SDH}	I^2C Serial data hold time	0		ns
t_{ICR}	I^2C Input rise time	20	300	ns
t_{ICF}	I^2C Input fall time	$20 \times (V_{DD} / 5.5)$	300	ns
t_{OCF}	I^2C Output fall time, 10 pF to 400 pF bus	$(V_{DD} / 5.5) \times 20$	300	ns
t_{BUF}	I^2C Bus free time between stop and start	1.3		µs
t_{STS}	I^2C Start or repeater start condition setup time	1.3		µs
t_{STH}	I^2C Start or repeater start condition hold time	0.6		µs
t_{SPS}	I^2C Stop condition setup time	0.6		µs
$t_{VD(DATA)}$	Valid data time, SCL low to SDA output valid		1	µs
$t_{VD(ACK)}$	Valid data time of ACK condition, ACK signal from SCL low to SDA (out) low		1	µs

7.7 Typical Characteristics

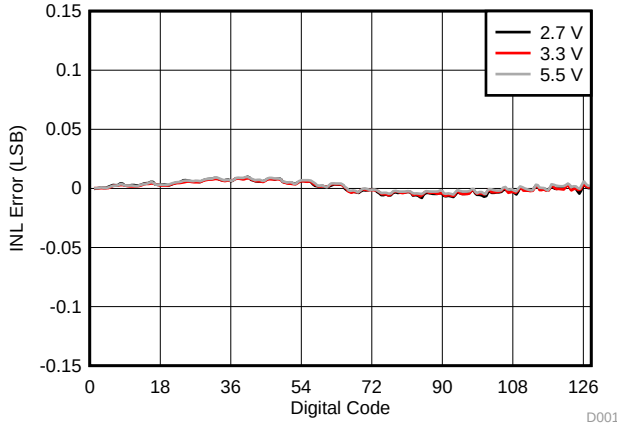


Figure 1. INL vs Tap Position (Potentiometer Mode)

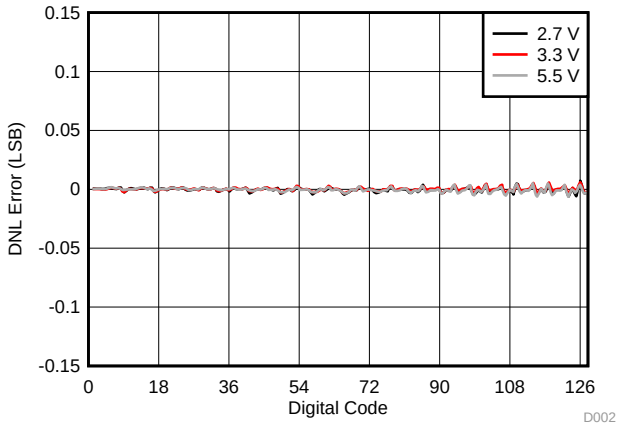


Figure 2. DNL vs Tap Position (Potentiometer Mode)

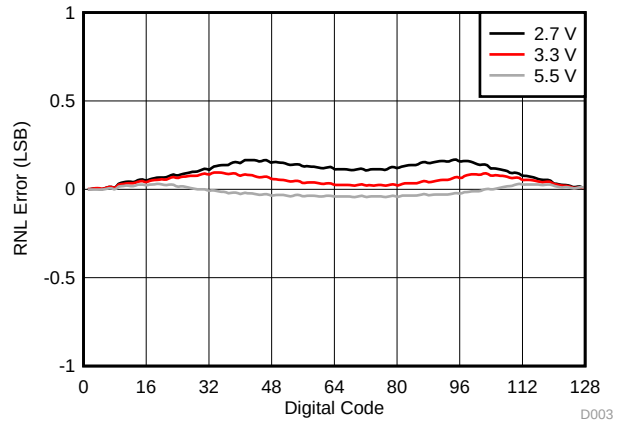


Figure 3. INL vs Tap Position (Rheostat Mode)

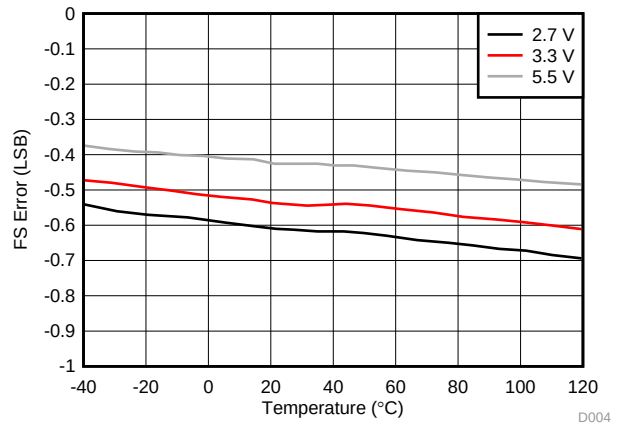


Figure 4. Full Scale Error vs Temperature

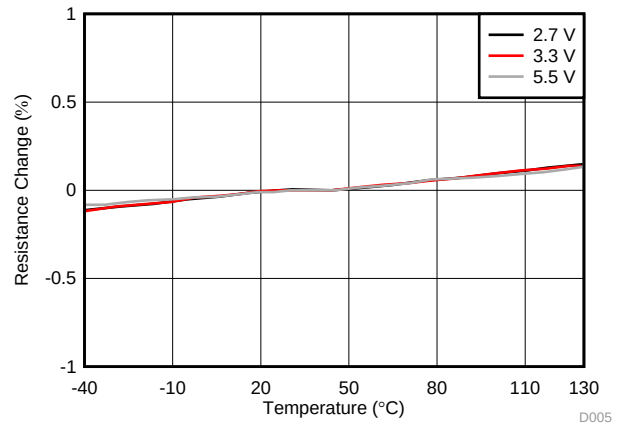


Figure 5. End-to-End R_{TOTAL} Change vs Temperature

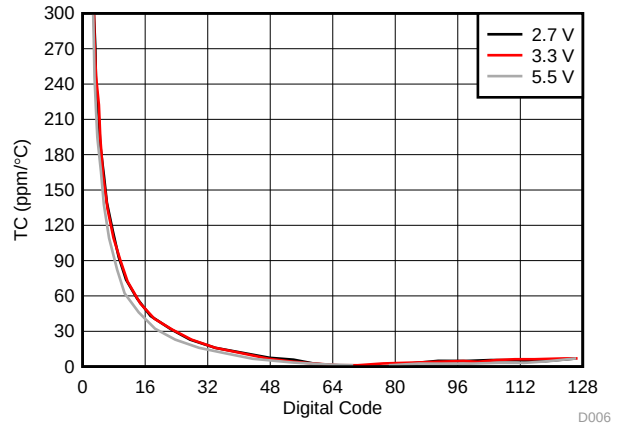


Figure 6. Temperature Coefficient vs TAP Position (Potentiometer Mode)

Typical Characteristics (continued)

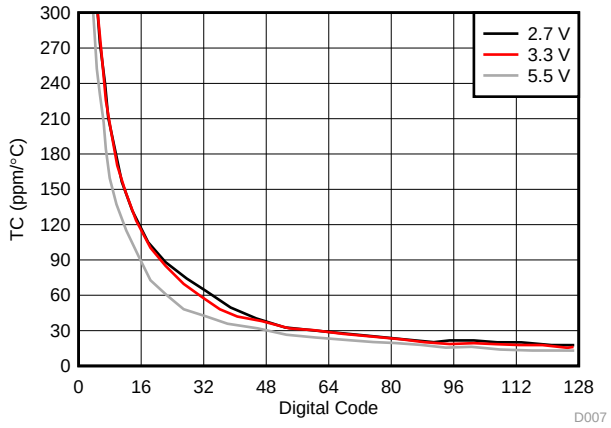


Figure 7. Temperature Coefficient vs TAP Position (Rheostat Mode)

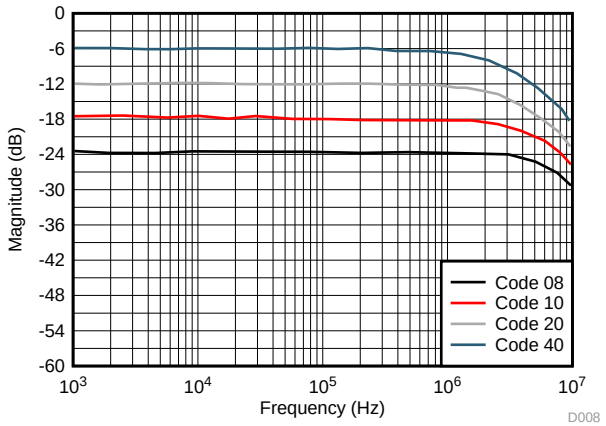
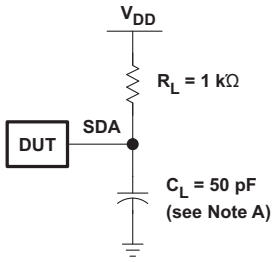
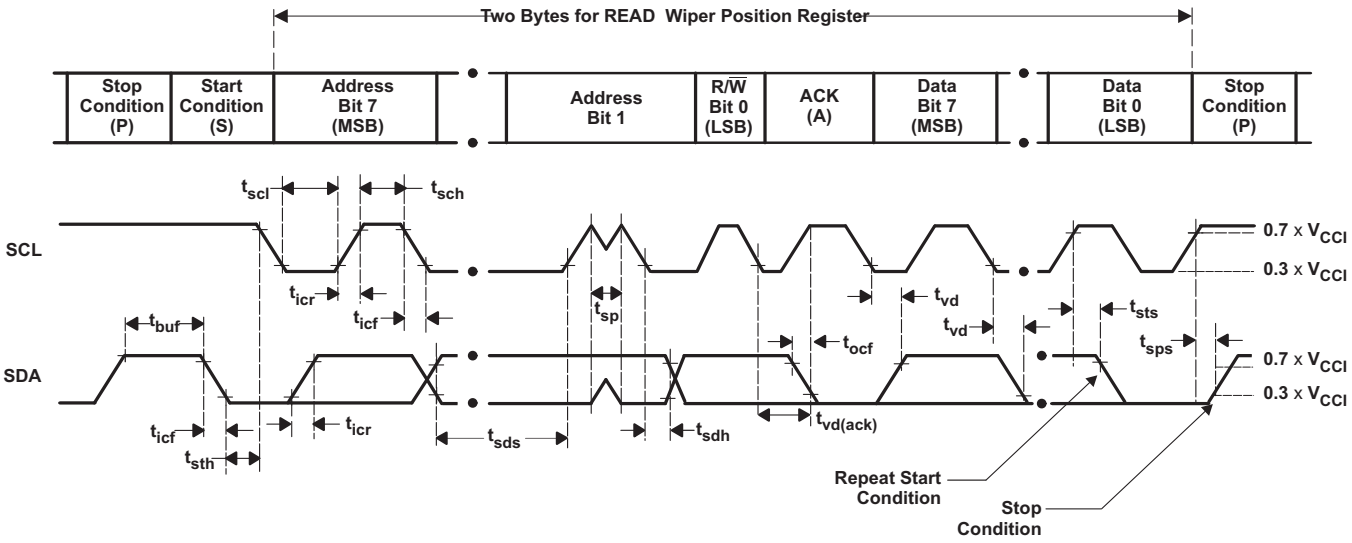


Figure 8. Frequency Response

8 Parameter Measurement Information



SDA LOAD CONFIGURATION



VOLTAGE WAVEFORMS

BYTE	DESCRIPTION
1	I^2C address
2	Wiper Position Data

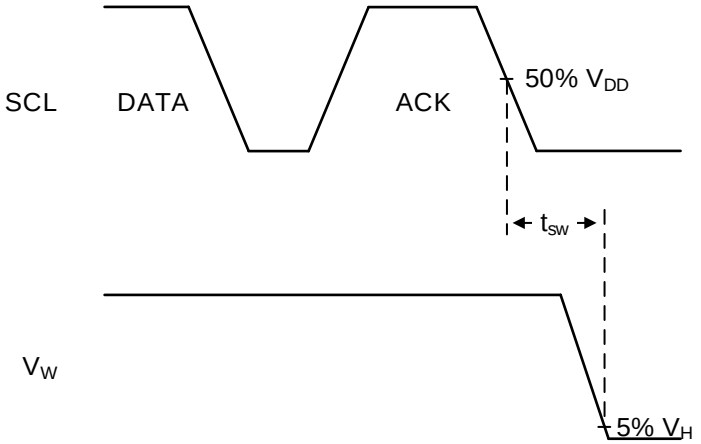
A. C_L includes probe and jig capacitance. tocf is measured with C_L of 10 pF or 400 pF.

B. All inputs are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r/t_f ≤ 30 ns.

C. All parameters and waveforms are not applicable to all devices.

Figure 9. I^2C Interface Load Circuit and Voltage Waveforms

Parameter Measurement Information (continued)



A. Code change is from 0×40 to 0×00

B. All inputs are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r/t_f ≤ 30 ns.

Figure 10. Switch Time Waveform (t_{SW})

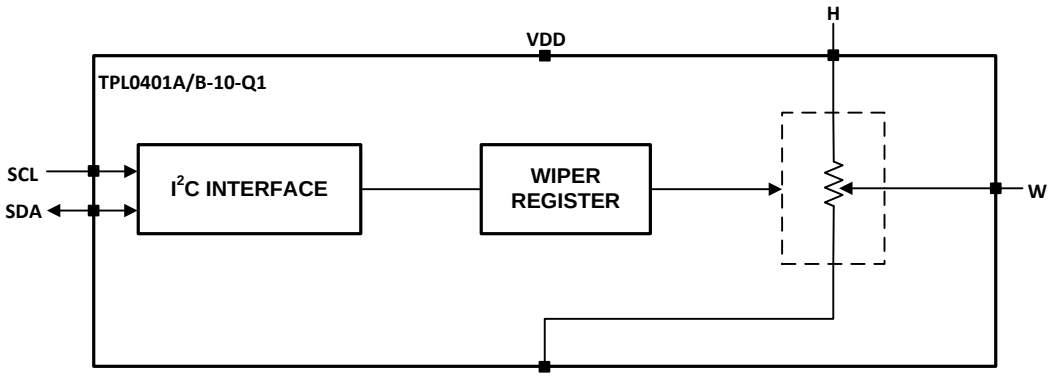
9 Detailed Description

9.1 Overview

The TPL0401x-10-Q1 has a single linear-taper digital potentiometer with 128 wiper positions and an end-to-end resistance of 10 kΩ. The potentiometer can be used as a three-terminal potentiometer. The main operation of TPL0401x-10-Q1 is in voltage divider mode.

The low (L) terminal of the TPL0401x-10-Q1 is tied directly to GND. The high (H) and low (GND) terminals of TPL0401-10-Q1 are equivalent to the fixed terminals of a mechanical potentiometer. The H terminal must have a higher voltage than the low terminal (GND). The position of the wiper (W) terminal is controlled by the value in the Wiper Resistance (WR) 8-bit register. When the WR register contains all zeroes (zero-scale), the wiper terminal is closest to its L terminal. As the value of the WR register increases from all zeroes to all ones (full-scale), the wiper moves from the position closest to the GND terminal to the position closest to the H terminal. At the same time, the resistance between W and GND increases, whereas the resistance between W and H decreases.

9.2 Functional Block Diagram



9.3 Feature Description

The TPL0401x-10-Q1 device is a single-channel, linear taper digital potentiometer with 128 wiper positions. Default power up state for the TPL0401x-10-Q1 is mid code (0×40). The TPL0401x-10-Q1 has the low terminal connected to GND internally. The position of the wiper can be adjusted using an I^2C interface. The TPL0401x-10-Q1 is available in a 6-pin SOT package with a specified temperature range of –40°C to +125°C. The part has a 10-kΩ end-to-end resistance and can operate with a supply voltage range of 2.7 V to 5.5 V. This kind of product is widely used in setting the voltage reference for low power DDR3 memory. The TPL0401x-10-Q1 has the low terminal internal and connected to GND.

9.4 Device Functional Modes

9.4.1 Voltage Divider Mode

The digital potentiometer generates a voltage divider when all three terminals are used. The voltage divider at wiper-to-H and wiper-to-GND is proportional to the input voltage at H to L (see Figure 11).

Device Functional Modes (continued)

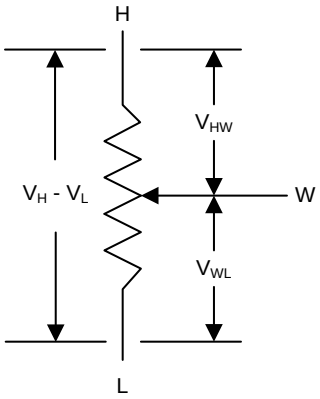


Figure 11. Equivalent Circuit for Voltage Divider Mode

For example, connecting terminal H to 5 V, the output voltage at terminal W can range from 0 V to 5 V. Equation 1 is the general equation defining the output voltage at terminal W for any valid input voltage applied to terminal H and terminal L (GND).

$$V_W = V_{WL} = (V_H - V_L) \times \frac{D}{128} \quad (1)$$

The voltage difference between terminal H and terminal W can also be calculated in Equation 2.

$$V_{HW} = (V_H - V_L) \times \left(1 - \left(\frac{D}{128}\right)\right) \quad (2)$$

where

- D is the decimal value of the wiper code

Table 1 shows the ideal values for DPOT with end-to end resistance of 10 kΩ. The absolute values of resistance can vary significantly but the Ratio (R_{WL}/R_{TOT}) is extremely accurate.

The linearity values are *relative* linearity values (that is, linearity after zero-scale and full-scale offset errors are removed). Consider this when expecting a certain absolute accuracy because some error is introduced when the device gets close in magnitude to the offset errors.

Note that the MSB is always discarded during a write to the wiper position register. For example, if 0×80 is written to the wiper position register, a read returns 0×00. Another similar example is if 0×FF is written, then 0×7F is read.

Table 1. Resistance Values Table

STEP	HEX	R_{WL} (KΩ)	R_{HW} (KΩ)	R_{WL}/R_{TOT}
0	0×00	0.00	10.00	0.0%
1	0×01	0.08	9.92	0.8%
2	0×02	0.16	9.84	1.6%
3	0×03	0.23	9.77	2.3%
4	0×04	0.31	9.69	3.1%
5	0×05	0.39	9.61	3.9%
6	0×06	0.47	9.53	4.7%
7	0×07	0.55	9.45	5.5%
8	0×08	0.63	9.38	6.3%
9	0×09	0.70	9.30	7.0%
10	0×0A	0.78	9.22	7.8%

Table 1. Resistance Values Table (continued)

STEP	HEX	R_{WL} (KΩ)	R_{HW} (KΩ)	R_{WL}/R_{TOT}
11	0×0B	0.86	9.14	8.6%
12	0×0C	0.94	9.06	9.4%
13	0×0D	1.02	8.98	10.2%
14	0×0E	1.09	8.91	10.9%
15	0×0F	1.17	8.83	11.7%
16	0×10	1.25	8.75	12.5%
17	0×11	1.33	8.67	13.3%
18	0×12	1.41	8.59	14.1%
19	0×13	1.48	8.52	14.8%
20	0×14	1.56	8.44	15.6%
21	0×15	1.64	8.36	16.4%
22	0×16	1.72	8.28	17.2%
23	0×17	1.80	8.20	18.0%
24	0×18	1.88	8.13	18.8%
25	0×19	1.95	8.05	19.5%
26	0×1A	2.03	7.97	20.3%
27	0×1B	2.11	7.89	21.1%
28	0×1C	2.19	7.81	21.9%
29	0×1D	2.27	7.73	22.7%
30	0×1E	2.34	7.66	23.4%
31	0×1F	2.42	7.58	24.2%
32	0×20	2.50	7.50	25.0%
33	0×21	2.58	7.42	25.8%
34	0×22	2.66	7.34	26.6%
35	0×23	2.73	7.27	27.3%
36	0×24	2.81	7.19	28.1%
37	0×25	2.89	7.11	28.9%
38	0×26	2.97	7.03	29.7%
39	0×27	3.05	6.95	30.5%
40	0×28	3.13	6.88	31.3%
41	0×29	3.20	6.80	32.0%
42	0×2A	3.28	6.72	32.8%
43	0×2B	3.36	6.64	33.6%
44	0×2C	3.44	6.56	34.4%
45	0×2D	3.52	6.48	35.2%
46	0×2E	3.59	6.41	35.9%
47	0×2F	3.67	6.33	36.7%
48	0×30	3.75	6.25	37.5%
49	0×31	3.83	6.17	38.3%
50	0×32	3.91	6.09	39.1%
51	0×33	3.98	6.02	39.8%
52	0×34	4.06	5.94	40.6%
53	0×35	4.14	5.86	41.4%
54	0×36	4.22	5.78	42.2%
55	0×37	4.30	5.70	43.0%
56	0×38	4.38	5.63	43.8%
57	0×39	4.45	5.55	44.5%

Table 1. Resistance Values Table (continued)

STEP	HEX	R_{WL} (KΩ)	R_{HW} (KΩ)	R_{WL}/R_{TOT}
58	0×3A	4.53	5.47	45.3%
59	0×3B	4.61	5.39	46.1%
60	0×3C	4.69	5.31	46.9%
61	0×3D	4.77	5.23	47.7%
62	0×3E	4.84	5.16	48.4%
63	0×3F	4.92	5.08	49.2%
64 (POR Default)	0×40	5.00	5.00	50.0%
65	0×41	5.08	4.92	50.8%
66	0×42	5.16	4.84	51.6%
67	0×43	5.23	4.77	52.3%
68	0×44	5.31	4.69	53.1%
69	0×45	5.39	4.61	53.9%
70	0×46	5.47	4.53	54.7%
71	0×47	5.55	4.45	55.5%
72	0×48	5.63	4.38	56.3%
73	0×49	5.70	4.30	57.0%
74	0×4A	5.78	4.22	57.8%
75	0×4B	5.86	4.14	58.6%
76	0×4C	5.94	4.06	59.4%
77	0×4D	6.02	3.98	60.2%
78	0×4E	6.09	3.91	60.9%
79	0×4F	6.17	3.83	61.7%
80	0×50	6.25	3.75	62.5%
81	0×51	6.33	3.67	63.3%
82	0×52	6.41	3.59	64.1%
83	0×53	6.48	3.52	64.8%
84	0×54	6.56	3.44	65.6%
85	0×55	6.64	3.36	66.4%
86	0×56	6.72	3.28	67.2%
87	0×57	6.80	3.20	68.0%
88	0×58	6.88	3.13	68.8%
89	0×59	6.95	3.05	69.5%
90	0×5A	7.03	2.97	70.3%
91	0×5B	7.11	2.89	71.1%
92	0×5C	7.19	2.81	71.9%
93	0×5D	7.27	2.73	72.7%
94	0×5E	7.34	2.66	73.4%
95	0×5F	7.42	2.58	74.2%
96	0×60	7.50	2.50	75.0%
97	0×61	7.58	2.42	75.8%
98	0×62	7.66	2.34	76.6%
99	0×63	7.73	2.27	77.3%
100	0×64	7.81	2.19	78.1%
101	0×65	7.89	2.11	78.9%
102	0×66	7.97	2.03	79.7%
103	0×67	8.05	1.95	80.5%
104	0×68	8.13	1.88	81.3%

Table 1. Resistance Values Table (continued)

STEP	HEX	R_{WL} (KΩ)	R_{HW} (KΩ)	R_{WL}/R_{TOT}
105	0×69	8.20	1.80	82.0%
106	0×6A	8.28	1.72	82.8%
107	0×6B	8.36	1.64	83.6%
108	0×6C	8.44	1.56	84.4%
109	0×6D	8.52	1.48	85.2%
110	0×6E	8.59	1.41	85.9%
111	0×6F	8.67	1.33	86.7%
112	0×70	8.75	1.25	87.5%
113	0×71	8.83	1.17	88.3%
114	0×72	8.91	1.09	89.1%
115	0×73	8.98	1.02	89.8%
116	0×74	9.06	0.94	90.6%
117	0×75	9.14	0.86	91.4%
118	0×76	9.22	0.78	92.2%
119	0×77	9.30	0.70	93.0%
120	0×78	9.38	0.63	93.8%
121	0×79	9.45	0.55	94.5%
122	0×7A	9.53	0.47	95.3%
123	0×7B	9.61	0.39	96.1%
124	0×7C	9.69	0.31	96.9%
125	0×7D	9.77	0.23	97.7%
126	0×7E	9.84	0.16	98.4%
127	0×7F	9.92	0.08	99.2%

9.5 Programming

9.5.1 I^2C General Operation and Overview

9.5.1.1 START and STOP Conditions

I^2C communication with this device is initiated by the master sending a START condition and terminated by the master sending a STOP condition. A high-to-low transition on the SDA line while the SCL is high defines a START condition. A low-to-high transition on the SDA line while the SCL is high defines a STOP condition. See Figure 12.

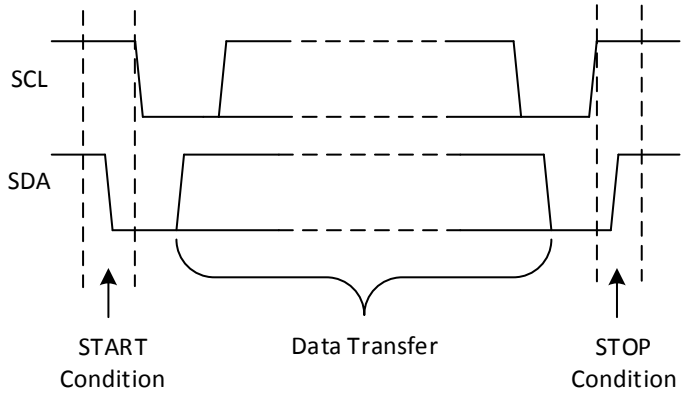


Figure 12. Definition of START and STOP Conditions

Programming (continued)

9.5.1.2 Data Validity and Byte Formation

One data bit is transferred during each clock pulse of the SCL. One byte is comprised of eight bits on the SDA line. See Figure 13. A byte may either be a device address, register address, or data written to or read from a slave.

Data is transferred Most Significant Bit (MSB) first. Any number of data bytes can be transferred from the master to slave between the START and STOP conditions. Data on the SDA line must remain stable during the high phase of the clock period, as changes in the data line when the SCL is high are interpreted as control commands (START or STOP).

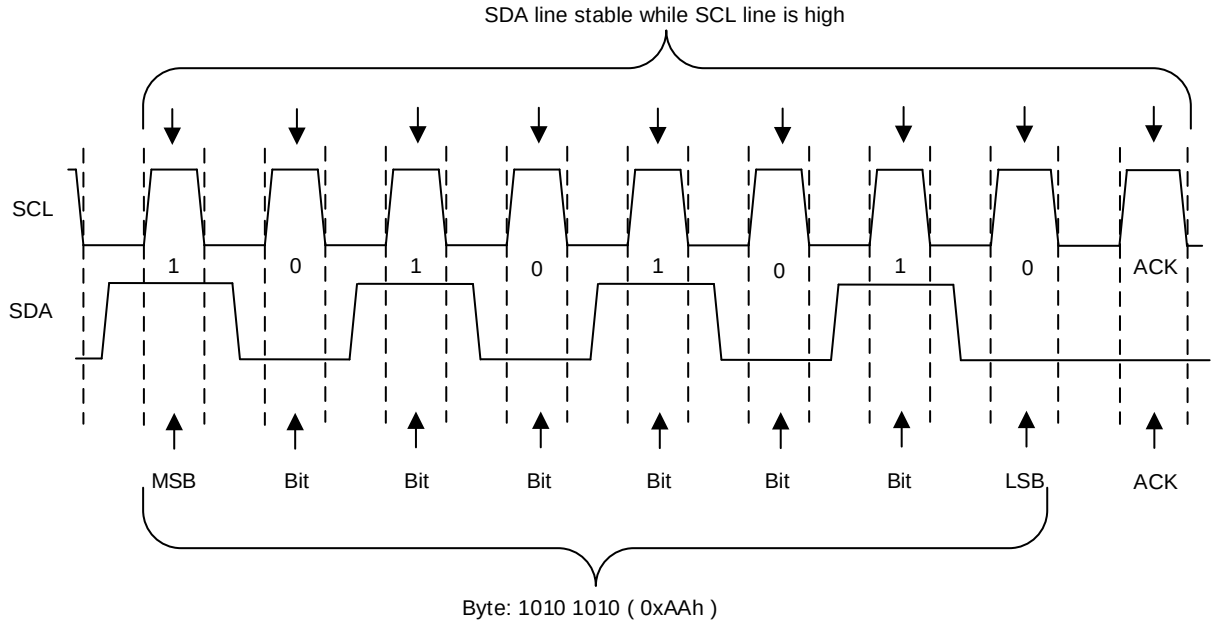


Figure 13. Definition of Byte Formation

9.5.1.3 Acknowledge (ACK) and Not Acknowledge (NACK)

Each byte is followed by one ACK bit from the receiver. The ACK bit allows the receiver to communicate to the transmitter that the byte was successfully received and another byte may be sent.

The transmitter must release the SDA line before the receiver can send the ACK bit. To send an ACK bit, the receiver shall pull down the SDA line during the low phase of the ACK/NACK-related clock period (period 9), so that the SDA line is stable low during the high phase of the ACK/NACK-related clock period. Consider setup and hold times. Figure 14 shows an example use of ACK.

Programming (continued)

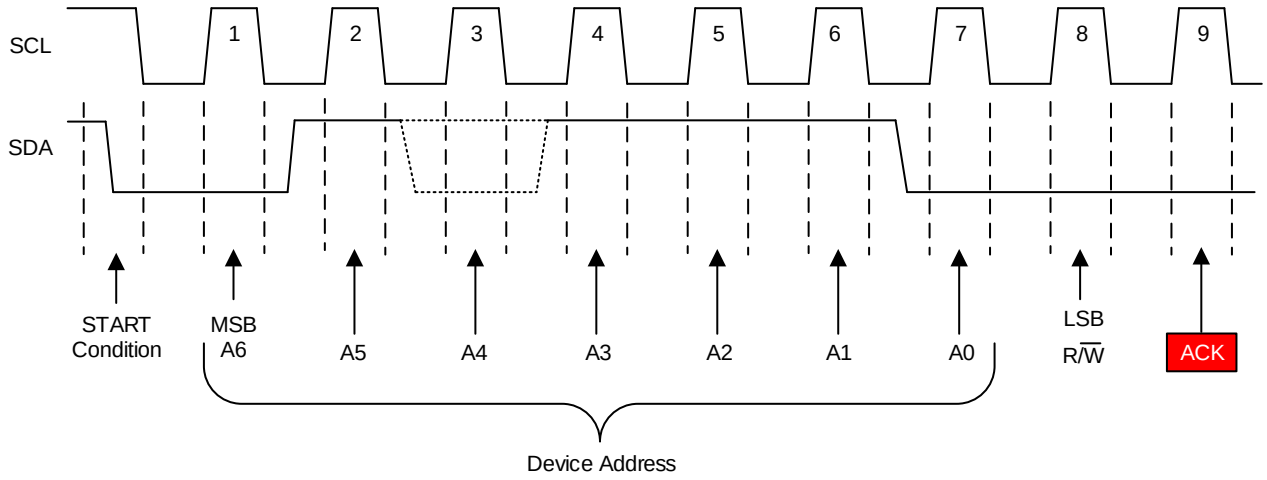


Figure 14. Example Use of ACK

When the SDA line remains high during the ACK/NACK-related clock period, this is a NACK signal. There are several conditions that lead to the generation of a NACK:

- The receiver is unable to receive or transmit because it is performing some real-time function and is not ready to start communication with the master.
- During the transfer, the receiver gets data or commands that it does not understand.
- During the transfer, the receiver cannot receive any more data bytes.
- A master-receiver is done reading data and indicates this to the slave through a NACK.

Figure 15 shows an example use of NACK.

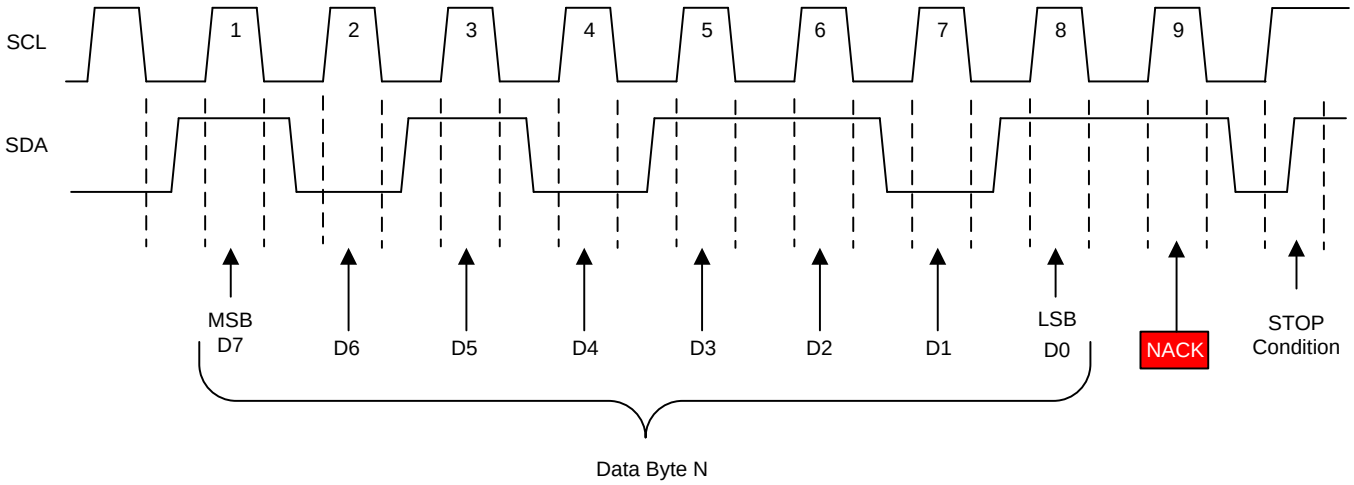


Figure 15. Example Use of NACK

9.5.1.4 Repeated Start

A repeated START condition may be used in place of a complete STOP condition follow by another START condition when performing a read function. The advantage of this is that the I^2C bus does not become available after the stop and therefore prevents other devices from grabbing the bus between transfers.

Programming (continued)

9.5.2 Programing With I²C

9.5.2.1 Write Operation

To write on the I²C bus, the master sends a START condition on the bus with the address of the slave, as well as the last bit (the R/$\overline{W}$ bit) set to 0, which signifies a write. After the slave responds with an acknowledge, the master then sends the register address of the register to which it wishes to write. The slave acknowledges again, letting the master know that it is ready. After this, the master starts sending the register data to the slave until the master has sent all the data necessary (which is sometimes only a single byte), and the master terminates the transmission with a STOP condition. See Figure 16.

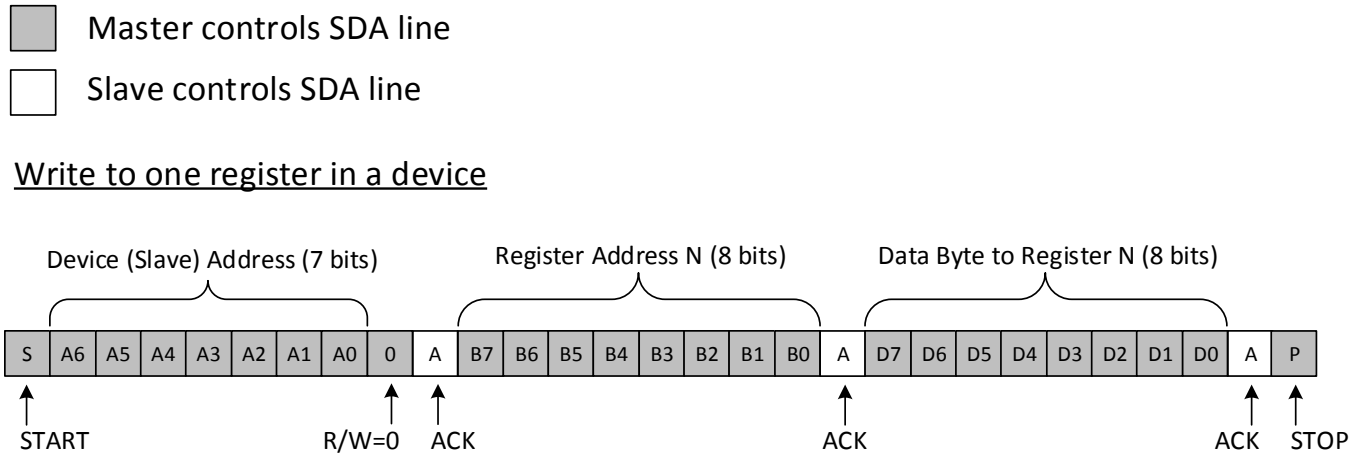


Figure 16. Write Operation

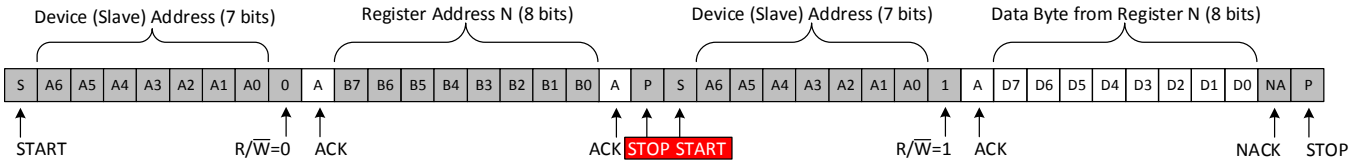
9.5.2.2 Read Operation

Reading from a slave is very similar to writing, but requires some additional steps. in order to read from a slave, the master must first instruct the slave which register it wishes to read from. This is done by the master starting off the transmission in a similar fashion as the write, by sending the address with the R/$\overline{W}$ bit equal to 0 (signifying a write), followed by the register address it wishes to read from. When the slave acknowledges this register address, the master sends a START condition again, followed by the slave address with the R/$\overline{W}$ bit set to 1 (Signifying a read). This time, the slave acknowledges the read request, and the master releases the SDA bus but continues supplying the clock to the slave. During this part of the transaction, the master becomes the master-receiver, and the slave becomes the slave-transmission.

The master continues to send out the clock pulses, for each byte of data that it wishes to receive. At the end of every byte of data, the master sends an ACK to the slave, letting the slave know that it is ready for more data. When the master has received the number of bytes it was expecting (or needs to stop communication), it sends a NACK, signaling to the slave to halt communications and release the bus. The master follows this up with a STOP condition. Figure 17 shows the read operation from one register.

Programming (continued)

Read from one register in a device



Read from one register in a device (Repeated Start)

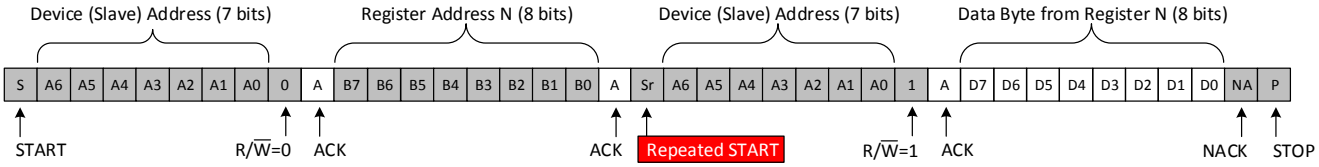


Figure 17. Read Operation from One Register

Read from one register in a device with single register

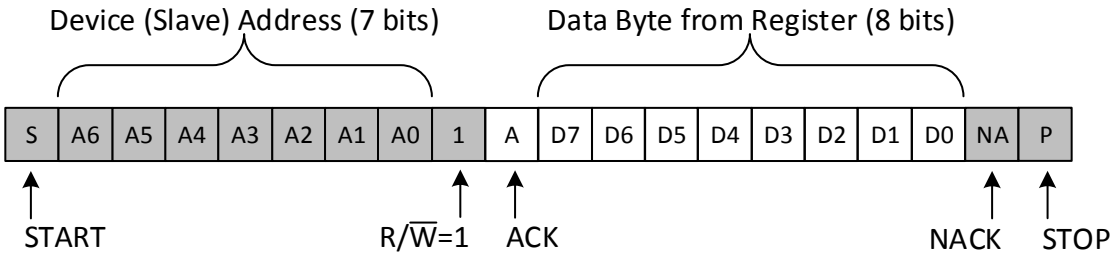


Figure 18. Short Read Operation

The TPL0401x-10-Q1 has 1 register, and it is not a requirement that the register address be sent before a read. A shorter read allows the user to simply send a read request to the device address as shown in Figure 18.

9.6 Register Maps

9.6.1 Slave Address

Table 2 and Table 3 show the TPL0401A-10-Q1 and TPL0401B-10-Q1 bit address repectively.

Table 2. TPL0401A-10-Q1 Bit Address

BIT 7 (MSB)	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0 (LSB)
0	1	0	1	1	1	0	R/W

Table 3. TPL0401B-10-Q1 Bit Address

BIT 7 (MSB)	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0 (LSB)
0	1	1	1	1	1	0	R/W

9.6.2 Register Address

Following the successful acknowledgment of the address byte, the bus master sends a command byte as shown in Figure 19, which is stored in the Control Register in the TPL0401x-10-Q1. The TPL0401x-10-Q1 has only 1 register, but requires the command byte be sent during communication.

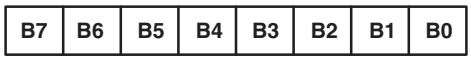


Figure 19. Register Address Byte

Table 4 shows the TPL0401x-10-Q1 register address byte.

Table 4. Register Address Byte

REGISTER ADDRESS BITS								REGISTER ADDRESS (HEX)	REGISTER	PROTOCOL	POWER-UP DEFAULT
B7	B6	B5	B4	B3	B2	B1	B0				
0	0	0	0	0	0	0	0	0×00	Wiper Position	Read/Write byte	0100 0000 (0×40)

See Table 1 for more information on the wiper position register values. Note that the MSB is always discarded during a write to the wiper position register. For example, if 0×80 is written to the wiper position register, a read returns 0×00. Another similar example is if 0×FF is written, then 0×7F is read.

10 Application and Implementation

10.1 Application Information

There are many applications in which voltage division is needed through the use of a digital potentiometer such as the TPL0401x-10-Q1; this is one example of the many. In conjunction with many amplifiers, the TPL0401x-10-Q1 can effectively be used in voltage divider mode to create a buffer to adjust the reference voltage for DDR3 DIMM1 Memory.

10.2 Typical Application

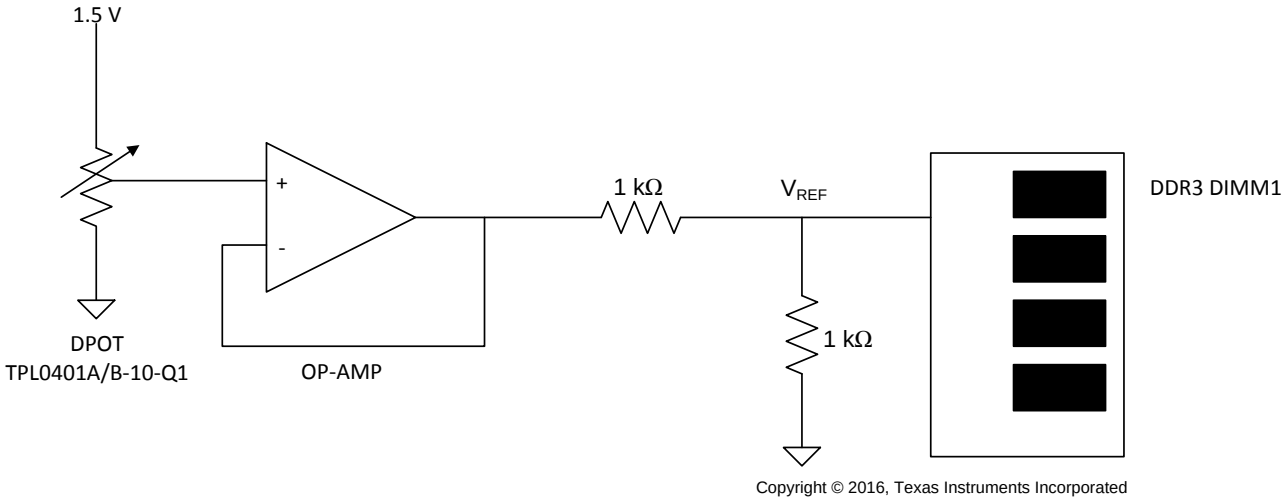


Figure 20. DDR3 Voltage Reference Adjustment

10.2.1 Design Requirements

Table 5 lists the design parameters for this example.

Table 5. Design Parameters

PARAMETER	EXAMPLE VALUE
Input voltage	1.5 V
V_{REF}	0 V to 0.75 V

10.2.2 Detailed Design Procedure

The TPL0401x-10-Q1 can be used in voltage divider mode with a unity-gain op amp buffer to provide a clean voltage reference for DDR3 DIMM1 Memory. The analog output voltage, V_{REF1} is determined by the wiper setting programmed through the I^2C bus.

The op amp is required to buffer the high-impedance output of the TPL0401x-10-Q1 or else loading placed on the output of the voltage divider affects the output voltage.

10.2.3 Application Curve

The voltage, 1.5 V, applied to terminal H of TPL0401x-10-Q1 determines the voltage that is buffered by the unity-gain op amp and divided as the DDR3 DIMM1 voltage reference. By using the TPL0401x-10-Q1, and dividing the 1.5 V, a maximum of 0.75 V is applied to the buffer and passed to the voltage divider. The output voltage then ranges from 0 V to 0.75 V.

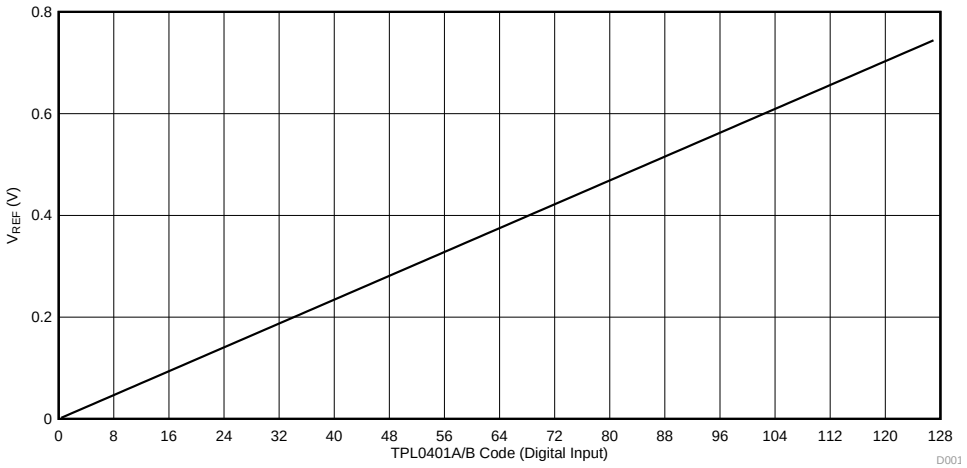


Figure 21. TPL0401-10-Q1 Digital Input vs Reference Voltage for DDR3 DIMM Memory

11 Power Supply Recommendations

11.1 Power Sequence

Protection diodes limit the voltage compliance at SDA, SCL, terminal H, and terminal W, making it important to power up V_{DD} first before applying any voltage to SDA, SCL, terminal H, and terminal W. The diodes are forward-biasing, meaning V_{DD} can be powered unintentionally if V_{DD} is not powered first. The ideal power-up sequence is V_{DD}, digital inputs, and V_W and V_H. The order of powering digital inputs, V_H and V_W does not matter as long as they are powered after V_{DD}.

11.2 Power-On Reset Requirements

In the event of a glitch or data corruption, the TPL0401-10-Q1 can be reset to its default conditions by using the power-on reset feature. Power-on reset requires that the device go through a power cycle to be completely reset. This reset also happens when the device is powered on for the first time in an application.

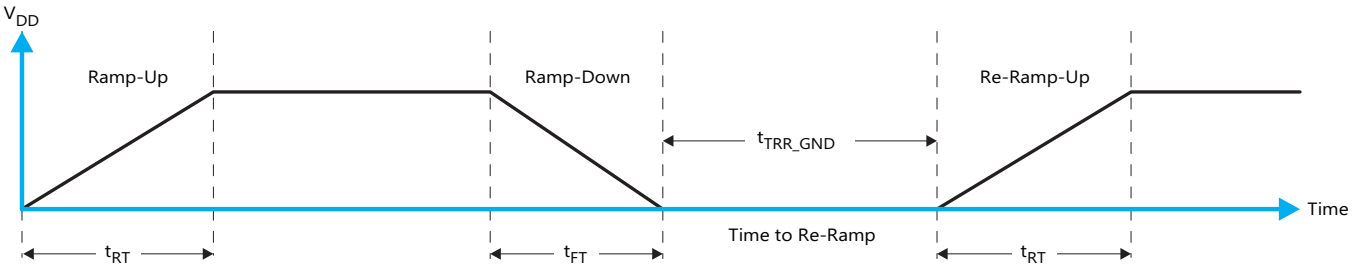


Figure 22. V_{DD} is Lowered to 0 V and then Ramped Up to V_{DD}

Table 6 specifies the performance of the power-on reset feature for TCA6408A for both types of power-on reset.

Table 6. Recommended Supply Sequencing and Ramp Rates at T_A = 25°C(1)

PARAMETER			MIN	MAX	UNIT
t_{FT}	Fall rate	See Figure 22	0.0001	1000	ms
t_{RT}	Rise rate	See Figure 22	0.0001	1000	ms
t_{RR_GND}	Time to re-ramp (when V_{DD} drops to GND)	See Figure 22	1		µs

(1) Not tested. Specified by design.

11.3 I²C Communication After Power Up

In order to ensure a complete device reset after a power up condition, the user must wait 120 µs after power up before initiating communication with the TPL0401x-10-Q1. See Figure 23 for an example waveform.

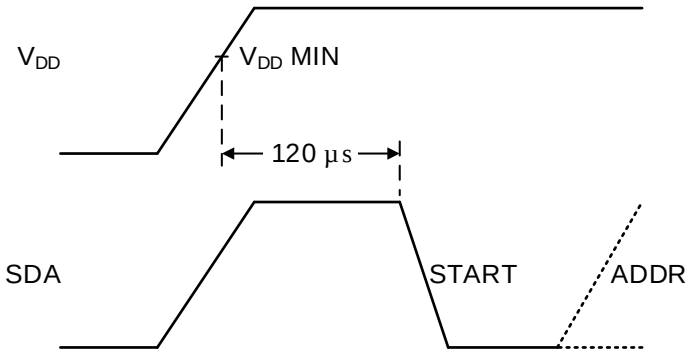


Figure 23. Recommended Start Up Sequence

11.4 Wiper Position While Unpowered and After Power Up

When DPOT is powered off, the impedance of the device is undefined and not known.

Upon power-up, the device returns to 0×40h code because this device does not contain non-volatile memory.

12 Layout

12.1 Layout Guidelines

To ensure reliability of the device, follow common printed-circuit board (PCB) layout guidelines:

- Leads to the input must be as direct as possible with a minimum conductor length.
- The ground path must have low resistance and low inductance.
- Use short trace-lengths to avoid excessive loading.
- It is common to have a dedicated ground plane on an inner layer of the board.
- Terminals that are connected to ground must have a low-impedance path to the ground plane in the form of wide polygon pours and multiple vias.
- Use bypass capacitors on power supplies and placed them as close as possible to the V_{DD} pin.
- Apply low equivalent series resistance (0.1-μF to 10-μF tantalum or electrolytic capacitors) at the supplies to minimize transient disturbances and to filter low-frequency ripple.
- To reduce the total I^2C bus capacitance added by PCB parasitics, data lines (SCL and SDA) must be as short as possible and the widths of the traces must also be minimized (for example, 5 to 10 mils depending on copper weight).

12.2 Layout Example

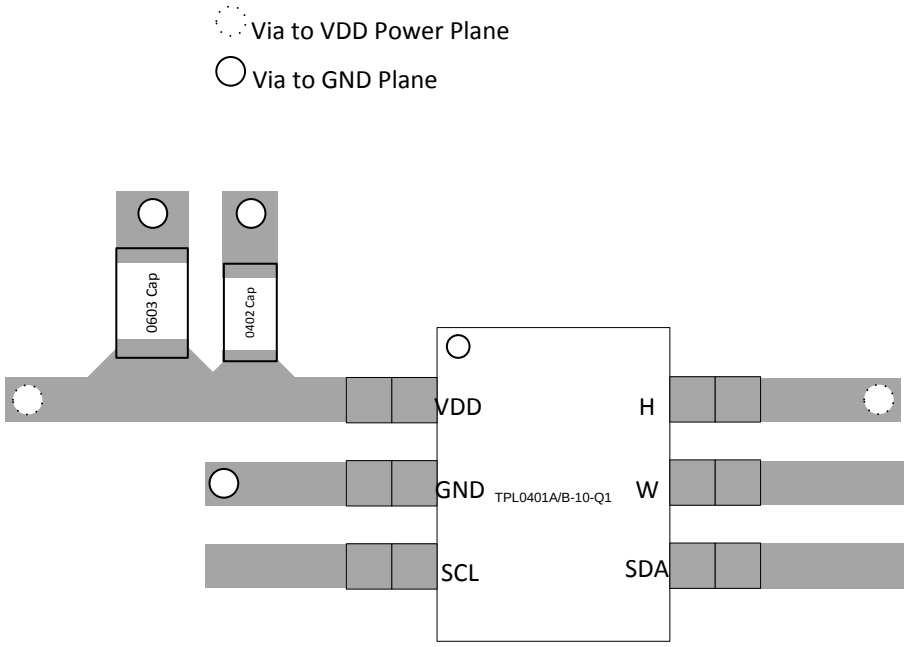


Figure 24. Layout Recommendation

13 デバイスおよびドキュメントのサポート

13.1 ドキュメントのサポート

13.1.1 関連資料

関連資料については、以下を参照してください。

- *『I²Cバスのプルアップ抵抗値の計算』*
- *『I²Cバスについて理解する』*
- *『TPL0401評価モジュール・ユーザーズ・ガイド』*

13.2 関連リンク

次の表に、クイック・アクセス・リンクを示します。カテゴリには、技術資料、サポートおよびコミュニティ・リソース、ツールとソフトウェア、およびサンプル注文またはご購入へのクイック・アクセスが含まれます。

表 7. 関連リンク

製品	プロダクト・フォルダ	サンプルとご購入	技術資料	ツールとソフトウェア	サポートとコミュニティ
TPL0401A-Q1	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
TPL0401B-Q1	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック

13.3 ドキュメントの更新通知を受け取る方法

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13.4 コミュニティ・リソース

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13.6 静電気放電に関する注意事項

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13.7 用語集

SLYZ022 — *TI用語集*.

この用語集には、用語や略語の一覧および定義が記載されています。

14 メカニカル、パッケージ、および注文情報

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPL0401A-10QDCKRQ1	ACTIVE	SC70	DCK	6	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	15N	Samples
TPL0401B-10QDCKRQ1	ACTIVE	SC70	DCK	6	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	15O	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

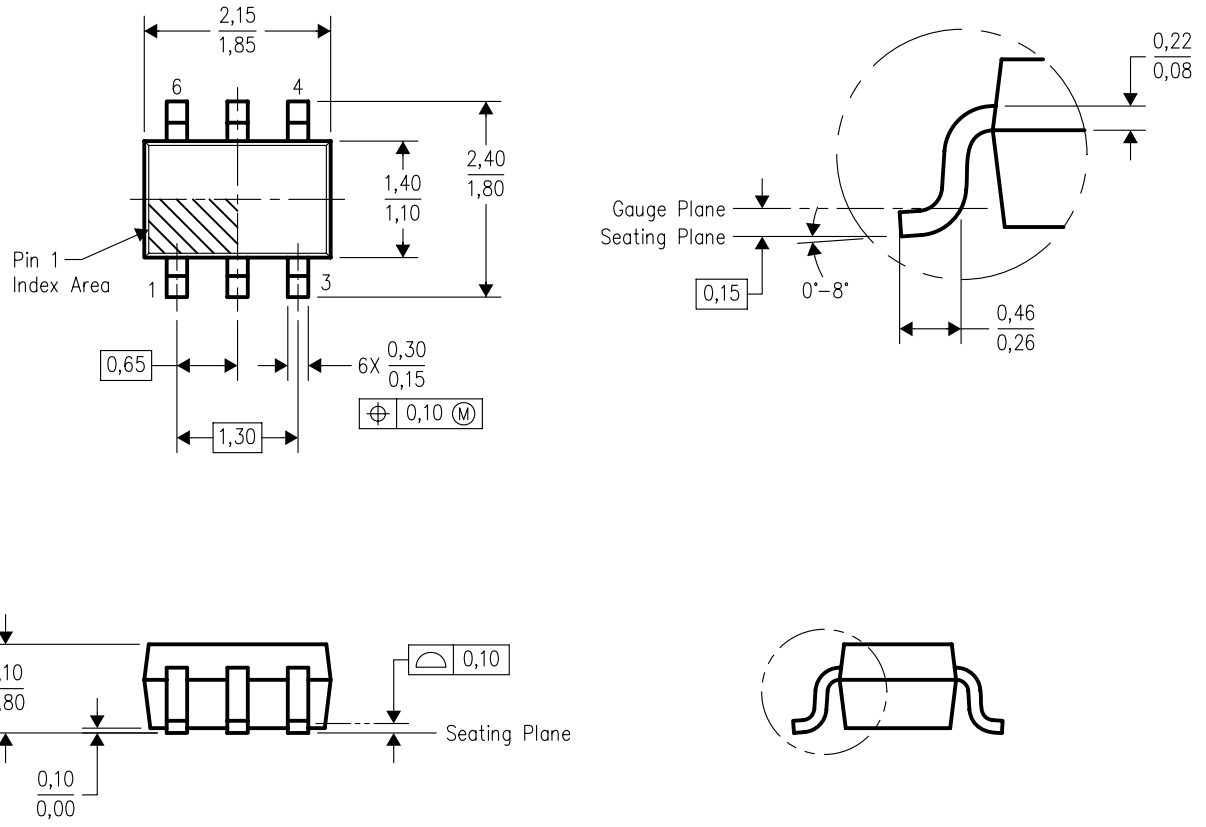
(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

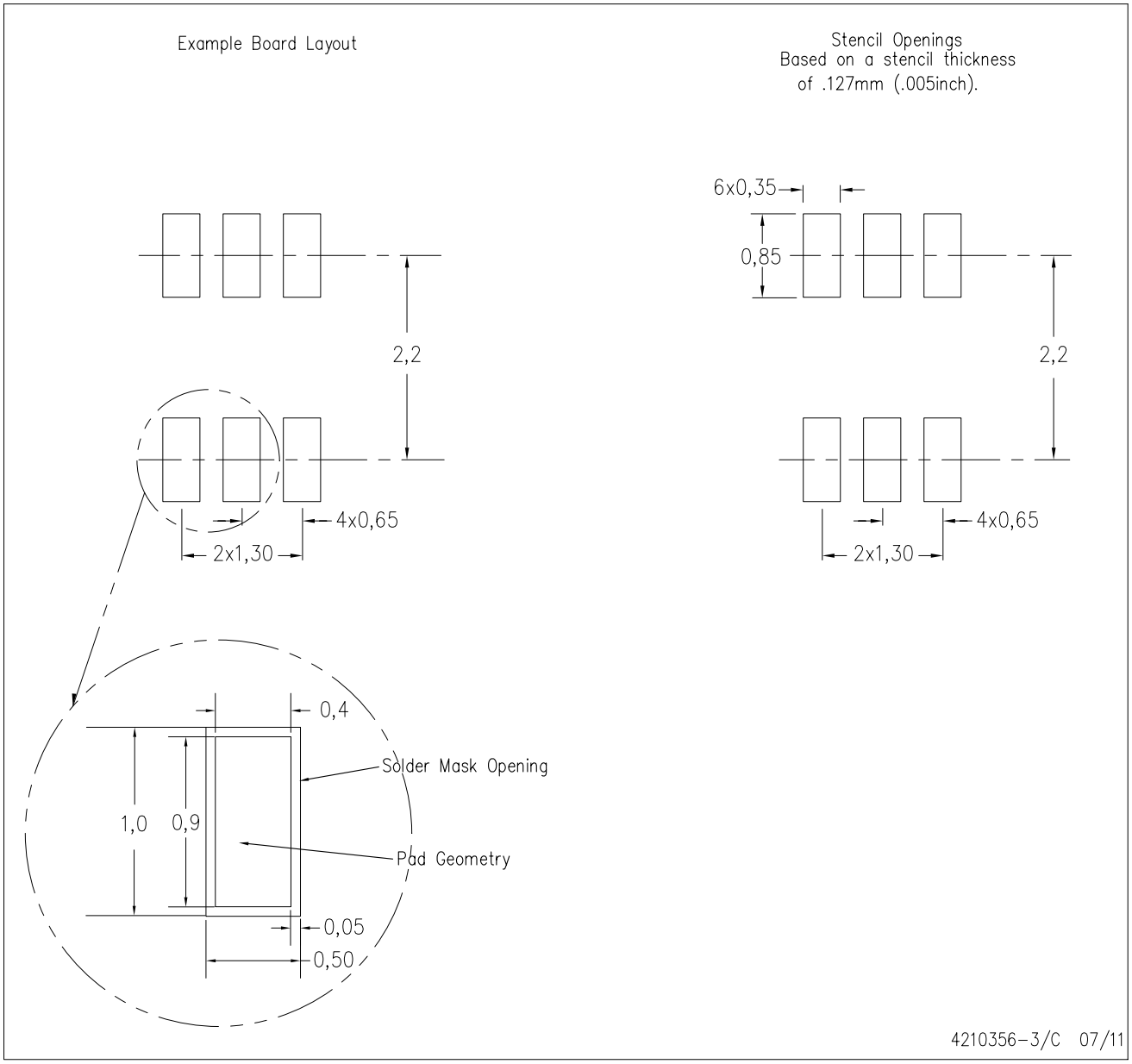
DCK (R–PDSO–G6) PLASTIC SMALL–OUTLINE PACKAGE



4093553–4/G 01/2007

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Falls within JEDEC MO–203 variation AB.

DCK (R–PDSO–G6) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
D. Publication IPC–7351 is recommended for alternate designs.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC–7525 for other stencil recommendations.

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